



## DETAIL "A"

LAYER BUILD UP  
(reference only)

(external Cu th are after plating)  
estimated total thickness 1650u

DRILL CHART: TOP TO BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	FINISHED SIZE	PLATED	QTY
A	12.0	PLATED	632
B	31.5	PLATED	29
C	40.0	PLATED	54
D	43.31	PLATED	2
E	51.0	PLATED	2
F	55.0	PLATED	8
G	125.98	NON-PLATED	4
TOTAL HOLES			731

Finished Hole Tolerance			
- All units are in Inches -			
Finished Hole Diameter	Plated Through Finished Hole Diameter	Non Plated Through Finished Hole Diameter	
0.008"-0.013"	+0.002/-FHS	+/-0.002"	
0.014"-0.063"	+/-0.003"	+/-0.002"	
0.064"-0.156"	+/-0.004"	+/-0.003"	
0.157"-0.250"	+/-0.007"	+/-0.004"	
0.251" and up	+/-0.007"	+/-0.005"	
0.125"	Non Plated Only	+0.003/-0.000"	

FABRICATION NOTE:

- 1: FABRICATE USING LATEST REVISION OF IPC-6012A CLASS 2 OR ABOVE
- 2: FABRICATE USING MASTER artwork EVLST01VE6 R1 FOR CIRCUIT PATTERN  
NO DEVIATION FROM MASTER artwork ARE PERMITTED WITHOUT WRITTEN  
APPROVAL FROM AN AUTHORIZED SMT electronics REPRESENTATIVE
- 3: VENDOR MUST BE UL QUALIFIED AND BOARDS MUST BE IDENTIFIED WITH  
APPROPRIATE VENDOR UL IDENTIFICATION MARK, LOT OR JOB NUMBER AND  
PCB MATERIAL FLAMMABILITY RATING (94V-0) MINIMUM
- 4: MATERIAL: FR4 RoHS COMPLIANT MINIMUM 170 C (High TG)  
SEE "DETAIL A-" FOR BOARD THICKNESS, COPPER WEIGHT AND LAYER CONSTRUCTION
- 5: GREEN SOLDER MASK BOTH SIDE OF BOARD WITH LIQUID PHOTO IMAGEABLE SOLDERMASK
- 6: FINISH: HAL Lead Free
- 7: FOR SMT COMPONENTS WITH PIN PITCH OF 0.019 INCH OR MORE NO GANG RELIEF  
OF SOLDER MASK IS ALLOWED
- 8: SILKSREEN TO BE WHITE, NON CONDUCTIVE, EPOXY INK OR EQUIVALENT
- 9: THIS IS NOT A CONTROLLED IMPEDANCE BOARD
- 10: DESIGNATED AREA OR INSPECTION AND TEST STAMP
- 11: ON BOTTOM PCB MUST BE IDENTIFIED MANUFACTURER LOGO AND PCB TYPE  
(MEANS OF MATERIAL TYPE INDICATED ON THE YELLOW CARD DOCUMENT)
- 12: VENDOR TO PROVIDE BOARD STACK-UP FOR IMPEDANCE APPROVAL PRIOR TO BOARD  
FABRICATION. STACK UP AND IMPEDANCE TO INCLUDE COPPER PLATING ON  
OUTER LAYERS. FAB DRAWING STACK-UP DIMENSION ARE PROVIDED FOR REFERENCE ONLY
- 13: VENDOR TO PROVIDE BOARD FOR IMPEDANCE TEST RESULTS AND COUPON  
TESTING TO INSURE A 2MIL ANULAR RING AT THE JUNCTION  
TO INSURE A 2MIL ANULAR RING AT THE JUNCTION
- 14: REMOVE SILKSREEN FROM SOLDERABLE SURFACE
- 15: ALL BOARD TO BE 100% ELECTRICALLY NETLIST TESTED FOR OPENS AND ON  
SHORTS.
- 16: THIS BOARD SHALL BE FULLY COMPLIANT WITH UL796

[illegible]